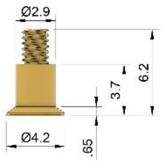
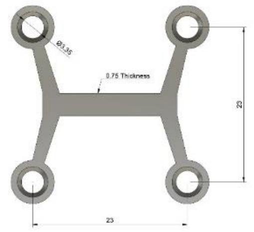
Cooling Solution

Cooling Solution for TX2 NX™

Heatsink / Heatspreader / Leaf spring

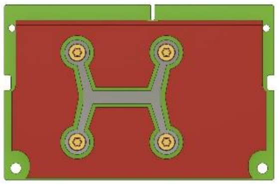
The TX2 NX leaf spring kits for secure mounting of cooling solutions.
This ensures optimal thermal interface while minimizing the risk of damaging the module.

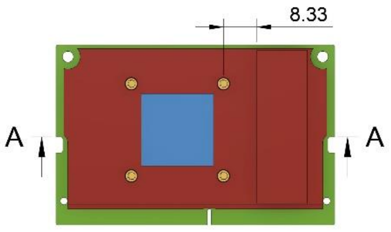


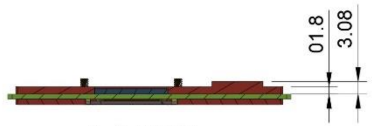


Implementation guidelines

- Refer to Nvidia Jetson TX2 NX Thermal Design Guide for thermal dissipation requirements
- Use M2x0.4 thread with at least 3mm depth fully formed thread in heatspreader/sink
- Recommended material for heatsink is aluminum or copper
- Use intermediate heat transfer compound (paste or pad), do not screw the module directly to heatsink/heatspreader or case
- When using heatspreader use thermal pad >0.5mm between heatspreader and case to ensure thermal conductivity
- Do not cover the module envelope
- Use <0.15Nm for M2 screws
- Handle module with care during assembly (ESD)
- Ensure correct orientation of the spring. The leaf spring should only contact the module in the middle
- SO-DIMM connector spacers must be used to reduce stress on the PCB







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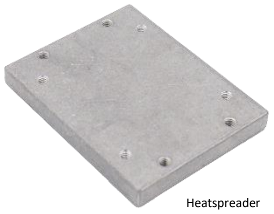
Heatsink with fan



Heatspreader

RED: module envelope, keep out zone for component clearance
BLUE: Processor die
GREEN: PCB + underside
The envelope for thermal solution 3D model is available in the Nvidia developer download area

Leaf spring kit TX2 NX:

Each kit includes
- Leaf spring (155-1019-000)
- 4 screws (155-1021-000)

Cooling kit TX2 NX:

Each kit includes
- Leaf spring (155-1019-000)
- 4 screws (155-1021-000)
- Heatsink with integrated fan (095-0102-000)

SKU	Kit
70841	Leaf spring kit TX2 NX
70842	Cooling kit TX2 NX
70756	Heatspreader 38x30x4.6mm
70757	Heatsink with fan (095-0102-000)

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